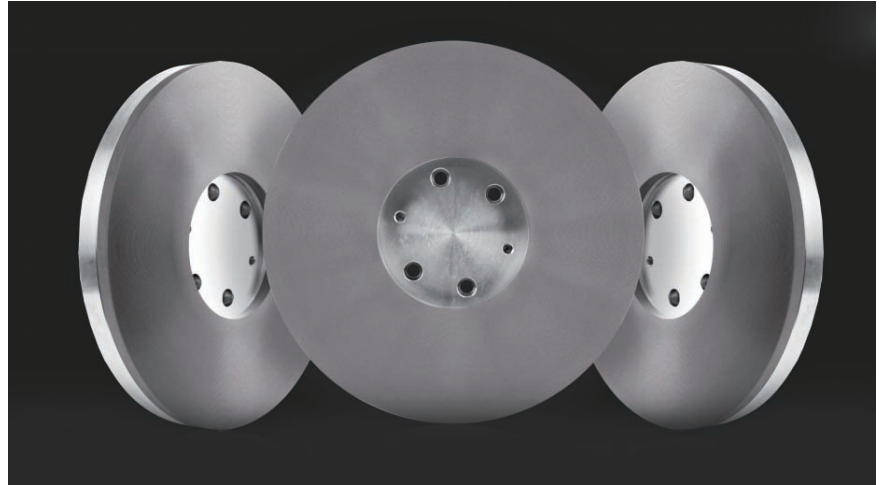


IRON-RESIN PLATE for Sapphire wafer (LED)



Advantages

- Excellent ductility minimizes the damages on the surface of wafers
- Providing the process specific plate in terms of Cut rate, Life time, and thermal stability
- Best solution for high-Precision polishing that requires zero defects on the surface of sapphire

Application

- Patterned sapphire wafer
- Bare sapphire wafer
- Bare silicon wafer

Specifications

Application	Outer Diameter(mm)	Inner Diameter(mm)	Thickness(mm)	Cut rate(mm)
Sapphire wafer	Ø510~Ø1100	Ø 50~ Ø 500	12~25	2.5~5.0
Lapping	- Plate dimensions and cut rate can adjusted upon customers' demands.			

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Performance Data

Parameters	Conditions
Pressure	400 g/cm ²
Plate velocity	90 rpm
Polisher	Single head type
Wafer	4 inch single crystalline sapphire wafer
Plate	Copper - Resin Plate Iron-Resin Plate
Slurry	Primary diameter 3 μ m
Slurry flowrate	4 ml/min

